

**CONTACT RATING:** Dependent upon contact material See Page 37.

**MECHANICAL LIFE:** 30,000 make-and-break cycles. **CONTACT RESISTANCE:** 20 m $\Omega$  max. initial @ 2-4VDC

100mA for both silver and gold plated contacts.

**INSULATION RESISTANCE:** 1,000 M $\Omega$  min.

DIELECTRIC STRENGTH: 1,000 Vrms min.@sea level.

OPERATING TEMPERATURE: -30°C to 85°C.

#### **MATERIALS**

CASE & BUSHING: Glass filled nylon 6/6,flame retardant,

heat stabilized (UL94v-0).

ACTUATOR: Brass, chrome plated, internal O-ring seal.

Standard for all actuators.

SWITCH SUPPORT: Brass,tin plated.

**CONTACT / TERMINALS:** Copper alloy, with Silver or gold plated.

(See Page 37)



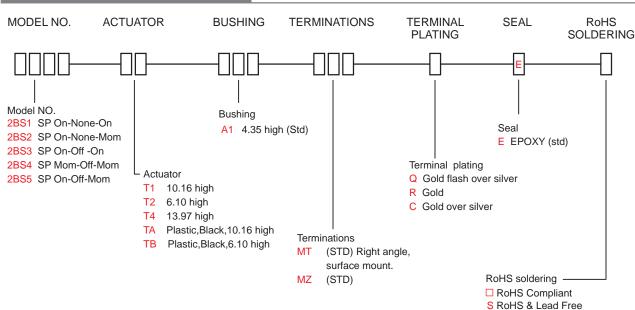








## HOW TO ORDER



## SWITCH FUNCTION



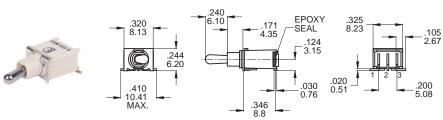
2B Toggle Switches

	SWITCH FUNCTION		CONNECTED TERMINALS / SCHEMATIC					
NO. POLES	MODEL NO.	MODEL NO.	POS.1	POS.2	POS.3	POS.1	POS.2	POS.3
	NO.		¥		#	7	<b>.</b>	<b>.</b>
SP	Q22B11	2BS1	ON	NONE	ON		N/A	2-1
	Q22B12	2BS2	ON	NONE	MOM	2-3		
	Q22B13	2BS3	ON	OFF	ON			
	Q22B14	2BS4	MOM	OFF	MOM	2 (COMM)	OPEN	2 (COMM) 1 • 3
	Q22B15	2BS5	ON	OFF	MOM	·		

MOM=MOMENTARY

#### **POLE OPTIONS**





P.C. MOUNTING

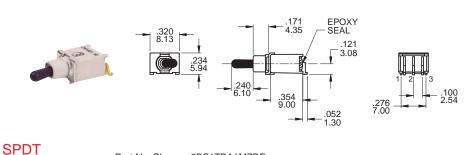
1.78
3.63
0.030
0.77
1.40
3.56
0.40
1.02
0.080
0.77
1.40
3.56
0.40
1.02

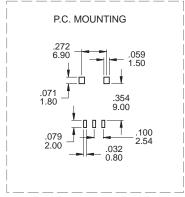
**SPDT** 

Part No. Shown: 2BS1T2A1MTRE

Part No. Shown: 2BS1TBA1MZRE

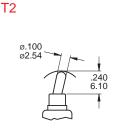
#### ΜZ

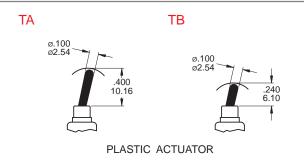




### **ACTUATOR OPTIONS**

Ø.100 Ø2.54 .400 10.16

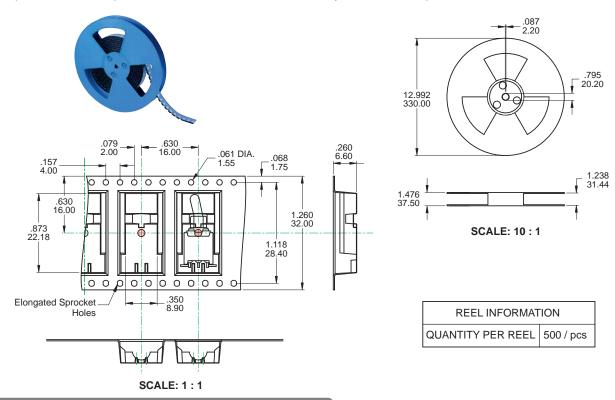




# **PACKAGING**

Switches available on embossed antistatic tape and reels.

Tape and cover strip are conductive for use near statically sensitive components.



### **CONTACT MATERIAL OPTIONS**

	CONTACT PLATING	TERMINAL PLATING	RATINGS		
Q	Silver	Q = Gold flash over silver	3 Amps with resistant load @ 120VAC or 28VDC		
С	Gold over Silver	C = Gold over silver	1 Amps with resistant load @ 250VAC		
R	Gold	R = Gold	0.4 Volt - Amps ( VA ) max. @ 20V max. ( AC or DC )		

### **SOLDERING PROCESSES**

#### WAVE SOLDERING:

Recommended Soldering Temperature: 260 ± 5°C Duration of Solder Immersion: Max 5 sec.

(PCB is 1.6mm in thickness)

**SOLDERING:** Vapor phase & IR-reflow soldering can be applied.

1	Pie-fie	at (A)	150	C		IVIIII 1205	
	Soak	(B)	180°C ~	200°C		Min 150s	
	Peak	(C)	200°C ~	235°C		Min 30s	
	Peak	(D)	235°C ~	260°C		Min 40s	
	Peak	(E)	260°	С		Max 5s	
(°0 25 20 15 10 50 Ro	0	A	Peak::		D E	Time (Sec)	

Temperature Profile